

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	196534	fuse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:29
L2	5568333	base substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:29
L3	259199	semiconductor adj L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:29
L4	3294623	plug via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:29
L5	8356	L4 near6 L3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:29
L6	48	L5 same L1 10/789980	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:50
L7	5845565	hole open\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:50
L8	415310	trim\$4 fuse	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:50
L9	9593031	(through therethrough penetrat\$4 reach\$4 extend\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:51
L10	1594090	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:52

L11	5568333	substrate base	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:53
L12	620861	10 adj 11 wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:53
L13	61699	9 near3 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:54
L14	10306	7 near9 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 17:55
L15	29	8 same 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:04
L16	38125	8.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:05
L17	1088374	7.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:11
L18	2188561	9.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:12
L19	98565	12.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:12
L20	55	16 same 17 same 18 same 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:12

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L20	55	16 same 17 same 18 same 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:20
L21	97	16 and 17 and 18 and 19	US-PGPUB	OR	ON	2005/12/01 18:14
L22	75208	(insulat\$4 dielectric).clm.	US-PGPUB	OR	ON	2005/12/01 18:15
L23	70	21 and 22	US-PGPUB	OR	ON	2005/12/01 18:16

L24	127469	{back inactive bottom}.clm.	US-PGPUB	OR	ON	2005/12/01 18:16
L25	22	23 and 24	US-PGPUB	OR	ON	2005/12/01 18:23
L26	17179	fuse.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 18:20